

ABSTRACT

Provided is a hollow cathode sputtering target comprising an inner bottom face having a surface roughness of $Ra \leq 1.0 \mu m$, and preferably $Ra \leq 0.5 \mu m$. This hollow cathode sputtering target has superior sputter film evenness (uniformity), generates few arcing and particles, is capable of suppressing the peeling of the redeposited film on the bottom face, and has superior deposition characteristics.